



March 2014

# Single-Channel: 6N135M, 6N136M, HCPL4503M Dual-Channel: HCPL2530M, HCPL2531M High Speed Transistor Optocouplers

## Features

- High Speed –1 MBit/s
- Superior CMR – 10 kV/μs
- Dual-Channel: HCPL2530M, HCPL2531M
- CTR Guaranteed 0°C to 70°C
- U.L. Recognized (File # E90700, Vol. 2)
- DIN EN/IEC60747-5-5
  - Ordering Option 'V', e.g., 6N135VM
- 5,000 V<sub>RMS</sub> (1 Minute) Isolation Rating
- Superior CMR of 15,000 V/μs Minimum (HCPL4503M)
- No Base Connection for Improved Noise Immunity (HCPL4503M)

## Applications

- Line Receivers
- Pulse Transformer Replacement
- Output Interface to CMOS-LSTTL-TTL
- Wide-Bandwidth Analog Coupling

## Description

The HCPL4503M, 6N135M, 6N136M, HCPL2530M, and HCPL2531M optocouplers consist of an AlGaAs LED optically coupled to a high speed photodetector transistor.

A separate connection for the bias of the photodiode improves the speed by several orders of magnitude over conventional phototransistor optocouplers by reducing the base-collector capacitance of the input transistor.

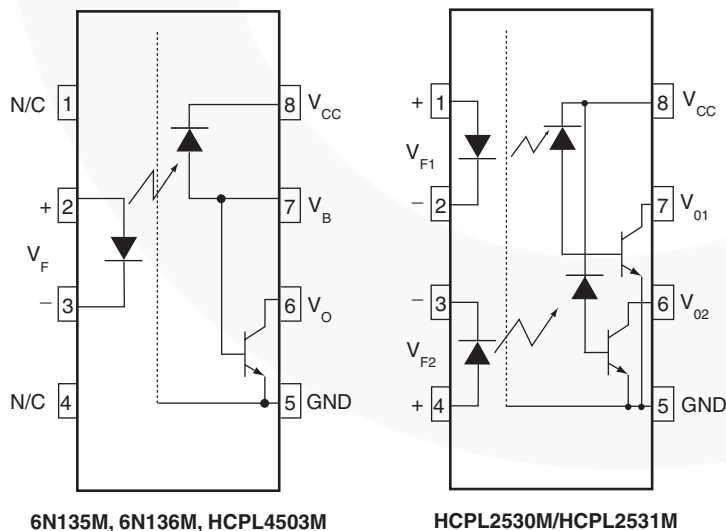
The HCPL4503M has no internal connection to the phototransistor base for improved noise immunity.

An internal noise shield provides superior common mode rejection of up to 50,000 V/μs.

## Related Resources

- [www.fairchildsemi.com/products/opto/](http://www.fairchildsemi.com/products/opto/)
- [www.fairchildsemi.com/pf/HC/HCPL0500.html](http://www.fairchildsemi.com/pf/HC/HCPL0500.html)
- [www.fairchildsemi.com/pf/FO/FODM452.html](http://www.fairchildsemi.com/pf/FO/FODM452.html)
- [www.fairchildsemi.com/pf/FO/FOD050L.html](http://www.fairchildsemi.com/pf/FO/FOD050L.html)

## Schematics



Pin 7 is not connected in the HCPL4503M

Figure 1. Schematics

## Package Outlines

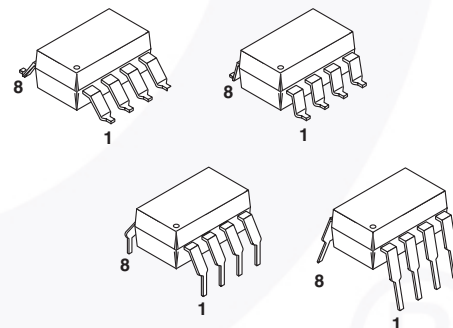


Figure 2. Package Outlines

## Safety and Insulation Ratings for 8-Pin DIP White

As per DIN EN/IEC 60747-5-5. This optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Typ.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For Rated Mains Voltage < 150 V <sub>RMS</sub>		I-IV		
	For Rated Mains Voltage < 300 V <sub>RMS</sub>		I-IV		
	For Rated Mains Voltage < 450 V <sub>RMS</sub>		I-III		
	For Rated Mains Voltage < 600 V <sub>RMS</sub>		I-III		
	Climatic Classification		40/100/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V <sub>PR</sub>	Input to Output Test Voltage, Method b, V <sub>IORM</sub> × 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1,669			
	Input to Output Test Voltage, Method a, V <sub>IORM</sub> × 1.5 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 60 s, Partial Discharge < 5 pC	1,335			
V <sub>IORM</sub>	Max Working Insulation Voltage	890			V <sub>PEAK</sub>
V <sub>IOTM</sub>	Highest Allowable Over Voltage	6,000			V <sub>PEAK</sub>
	External Creepage	8.0			mm
	External Clearance	7.4			mm
	External Clearance (for Option T, 0.4" Lead Spacing)	10.16			mm
	Insulation Thickness	0.5			mm
	Safety Limit Values, Maximum Values Allowed in the Event of a Failure				
T <sub>S</sub>	Case Temperature	150			°C
I <sub>S,INPUT</sub>	Input Current	200			mA
P <sub>S,OUTPUT</sub>	Output Power (Duty Factor ≤ 2.7%)	300			mW
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V	10 <sup>9</sup>			Ω

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Condition	Value	Units
$T_{STG}$	Storage Temperature		-40 to +125	$^\circ\text{C}$
$T_{OPR}$	Operating Temperature		-40 to +100	$^\circ\text{C}$
$T_{SOL}$	Lead Solder Temperature		260 for 10 s	$^\circ\text{C}$
<b>EMITTER</b>				
$I_F$ (avg)	DC/Average Forward Input Current Each Channel <sup>(1)</sup>		25	mA
$I_F$ (pk)	Peak Forward Input Current Each Channel <sup>(2)</sup>	50% Duty Cycle, 1 ms P.W.	50	mA
$I_F$ (trans)	Peak Transient Input Current Each Channel	$\leq 1 \mu\text{s}$ P.W., 300 pps	1.0	A
$V_R$	Reverse Input Voltage Each Channel		5	V
$P_D$	Input Power Dissipation Each Channel <sup>(3)</sup>	6N135M, 6N136M, and HCPL4503M	45	mW
		HCPL2530M and HCPL2531M		
<b>DETECTOR</b>				
$I_O$ (avg)	Average Output Current Each Channel		8	mA
$I_O$ (pk)	Peak Output Current Each Channel		16	mA
$V_{EBR}$	Emitter-Base Reverse Voltage	6N135M and 6N136M	5	V
$V_{CC}$	Supply Voltage		-0.5 to 30	V
$V_O$	Output Voltage		-0.5 to 20	V
$I_B$	Base Current	6N135M and 6N136M	5	mA
PD	Output Power Dissipation Each Channel <sup>(4)</sup>	6N135M, 6N136M, and HCPL4503M	100	mW
		HCPL2530M and HCPL2531M	35	mW

### Notes:

1. Derate linearly above  $70^\circ\text{C}$  free-air temperature at a rate of  $0.8 \text{ mA}/^\circ\text{C}$ .
2. Derate linearly above  $70^\circ\text{C}$  free-air temperature at a rate of  $1.6 \text{ mA}/^\circ\text{C}$ .
3. Derate linearly above  $70^\circ\text{C}$  free-air temperature at a rate of  $0.9 \text{ mW}/^\circ\text{C}$ .
4. Derate linearly above  $70^\circ\text{C}$  free-air temperature at a rate of  $2.0 \text{ mW}/^\circ\text{C}$ .

## Electrical Characteristics

$T_A = 0^\circ\text{C}$  to  $70^\circ\text{C}$  unless otherwise specified. Typical value is measured at  $T_A = 25^\circ\text{C}$  and  $V_{CC} = 5.0\text{ V}$ .

### Individual Component Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Typ.	Max.	Unit
<b>EMITTER</b>							
$V_F$	Input Forward Voltage	$I_F = 16\text{ mA}$ , $T_A = 25^\circ\text{C}$	All		1.45	1.7	V
		$I_F = 16\text{ mA}$	All			1.8	
$B_{VR}$	Input Reverse Breakdown Voltage	$I_R = 10\text{ }\mu\text{A}$	All	5.0	21		V
$\Delta V_F/\Delta T_A$	Temperature Coefficient of Forward Voltage	$I_F = 16\text{ mA}$	All		-1.7		mV/ $^\circ\text{C}$
<b>DETECTOR</b>							
$I_{OH}$	Logic High Output Current	$I_F = 0\text{ mA}$ , $V_O = V_{CC} = 5.5\text{ V}$ , $T_A = 25^\circ\text{C}$	All		0.0007	0.5	$\mu\text{A}$
		$I_F = 0\text{ mA}$ , $V_O = V_{CC} = 15\text{ V}$ , $T_A = 25^\circ\text{C}$	6N135M 6N136M HCPL4503M		0.0019	1	
		$I_F = 0\text{ mA}$ , $V_O = V_{CC} = 15\text{ V}$	All			50	
$I_{CCL}$	Logic Low Supply Current	$I_F = 16\text{ mA}$ , $V_O = \text{Open}$ , $V_{CC} = 15\text{ V}$	6N135M 6N136M HCPL4503M		163	200	$\mu\text{A}$
		$I_{F1} = I_{F2} = 16\text{ mA}$ , $V_O = \text{Open}$ , $V_{CC} = 15\text{ V}$	HCPL2530M HCPL2531M			400	
$I_{CCH}$	Logic High Supply Current	$I_F = 0\text{ mA}$ , $V_O = \text{Open}$ , $V_{CC} = 15\text{ V}$ , $T_A = 25^\circ\text{C}$	6N135M 6N136M HCPL4503M		0.0002	1	$\mu\text{A}$
		$I_F = 0\text{ mA}$ , $V_O = \text{Open}$ , $V_{CC} = 15\text{ V}$	6N135M 6N136M HCPL4503M		0.0004	2	
		$I_F = 0\text{ mA}$ , $V_O = \text{Open}$ , $V_{CC} = 15\text{ V}$	HCPL2530M HCPL2531M			4	

## Electrical Characteristics (Continued)

$T_A = 0$  to  $70^\circ\text{C}$  unless otherwise specified. Typical value is measured at  $T_A = 25^\circ\text{C}$  and  $V_{CC} = 5.0\text{ V}$ .

### Transfer Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Typ.	Max.	Unit	
<b>COUPLED</b>								
CTR	Current Transfer Ratio <sup>(5)</sup>	$I_F = 16\text{ mA}, V_O = 0.4\text{ V}, V_{CC} = 4.5\text{ V}, T_A = 25^\circ\text{C}$	6N135M	7	38	50	%	
			HCPL2530M					
			6N136M HCPL4503M	19	38	50	%	
			HCPL2531M					
		$I_F = 16\text{ mA}, V_{CC} = 4.5\text{ V}$	$V_{OL} = 0.4\text{ V}$	6N135M	5			%
			$V_{OL} = 0.5\text{ V}$	HCPL2530M				
			$V_{OL} = 0.4\text{ V}$	6N136M HCPL4503M	15			%
			$V_{OL} = 0.5\text{ V}$	HCPL2531M				
$V_{OL}$	Logic LOW Output Voltage	$I_F = 16\text{ mA}, I_O = 1.1\text{ mA}, V_{CC} = 4.5\text{ V}, T_A = 25^\circ\text{C}$	6N135M		0.12	0.4	V	
			HCPL2530M					
		$I_F = 16\text{ mA}, I_O = 3\text{ mA}, V_{CC} = 4.5\text{ V}, T_A = 25^\circ\text{C}$	6N136M HCPL4503M		0.20	0.4		
			HCPL2531M					
		$I_F = 16\text{ mA}, I_O = 0.8\text{ mA}, V_{CC} = 4.5\text{ V}$	6N135M		0.11	0.5		
			HCPL2530M					
		$I_F = 16\text{ mA}, I_O = 2.4\text{ mA}, V_{CC} = 4.5\text{ V}$	HCPL4503M		0.18	0.5		
			HCPL2531M					

**Note:**

5. Current Transfer Ratio is defined as a ratio of output collector current,  $I_O$ , to the forward LED input current,  $I_F$ , times 100%.

### Electrical Characteristics (Continued)

$T_A = 0$  to  $70^\circ\text{C}$  unless otherwise specified. Typical values are measured at  $T_A = 25^\circ\text{C}$  and  $V_{CC} = 5\text{V}$ .

#### Switching Characteristics ( $V_{CC} = 5\text{V}$ )

Symbol	Parameter	Test Conditions	Device	Min.	Typ.	Max.	Unit
$t_{PHL}$	Propagation Delay Time to Logic LOW	$T_A = 25^\circ\text{C}$ , $R_L = 4.1\text{ k}\Omega$ , $I_F = 16\text{ mA}^{(6)}$ (Figure 15)	6N135M		0.23	1.5	$\mu\text{s}$
			HCPL2530M				
		$R_L = 1.9\text{ k}\Omega$ , $I_F = 16\text{ mA}$ , $T_A = 25^\circ\text{C}^{(7)}$ (Figure 15)	6N136M		0.25	0.8	$\mu\text{s}$
			HCPL4503M HCPL2531M				
$t_{PLH}$	Propagation Delay Time to Logic HIGH	$T_A = 25^\circ\text{C}$ , ( $R_L = 4.1\text{ k}\Omega$ , $I_F = 16\text{ mA}^{(6)}$ ) (Figure 15)	6N135M		0.45	1.5	$\mu\text{s}$
			HCPL2530M				
		$R_L = 1.9\text{ k}\Omega$ , $I_F = 16\text{ mA}^{(7)}$ , $T_A = 25^\circ\text{C}$ (Figure 15)	6N136M		0.26	0.8	$\mu\text{s}$
			HCPL4503M HCPL2531M				
$ICM_{HI}$	Common Mode Transient Immunity at Logic High	$I_F = 0\text{ mA}$ , $V_{CM} = 10\text{ V}_{P-P}$ , $R_L = 4.1\text{ k}\Omega$ , $T_A = 25^\circ\text{C}^{(8)}$ (Figure 16)	6N135M		10,000		$\text{V}/\mu\text{s}$
			HCPL2530M				
		$I_F = 0\text{ mA}$ , $V_{CM} = 10\text{ V}_{P-P}$ , $R_L = 1.9\text{ k}\Omega$ , $T_A = 25^\circ\text{C}^{(8)}$ (Figure 16)	6N136M		10,000		$\text{V}/\mu\text{s}$
			HCPL4503M	15,000	50,000		
$ICM_{LI}$	Common Mode Transient Immunity at Logic Low	$I_F = 16\text{ mA}$ , $V_{CM} = 10\text{ V}_{P-P}$ , $R_L = 4.1\text{ k}\Omega$ , $T_A = 25^\circ\text{C}^{(8)}$ (Figure 16)	6N135M		10,000		$\text{V}/\mu\text{s}$
			HCPL2530M				
		$I_F = 16\text{ mA}$ , $V_{CM} = 10\text{ V}_{P-P}$ , $R_L = 1.9\text{ k}\Omega^{(8)}$ (Figure 16)	6N136M		10,000		$\text{V}/\mu\text{s}$
			HCPL2531M				
		$I_F = 0\text{ mA}$ , $V_{CM} = 1,500\text{ V}_{P-P}$ , $R_L = 1.9\text{ k}\Omega$ , $T_A = 25^\circ\text{C}^{(8)}$ (Figure 16)	HCPL4503M	15,000	50,000		

#### Notes:

- The 4.1 k $\Omega$  load represents 1 LSTTL unit load of 0.36 mA and 6.1 k $\Omega$  pull-up resistor.
- The 1.9 k $\Omega$  load represents 1 TTL unit load of 1.6 mA and 5.6 k $\Omega$  pull-up resistor.
- Common mode transient immunity in logic high level is the maximum tolerable (positive)  $dV_{cm}/dt$  on the leading edge of the common mode pulse signal  $V_{CM}$ , to assure that the output will remain in a logic high state (i.e.,  $V_O > 2.0\text{ V}$ ). Common mode transient immunity in logic low level is the maximum tolerable (negative)  $dV_{cm}/dt$  on the trailing edge of the common mode pulse signal,  $V_{CM}$ , to assure that the output will remain in a logic low state (i.e.,  $V_O < 0.8\text{ V}$ ).

## Electrical Characteristics (Continued)

$T_A = 0$  to  $70^\circ\text{C}$  unless otherwise specified. Typical values are measured at  $T_A = 25^\circ\text{C}$  and  $V_{CC} = 5\text{ V}$ .

### Isolation Characteristics

Symbol	Characteristics	Test Conditions	Min.	Typ.	Max.	Unit
$V_{ISO}$	Withstand Insulation Test Voltage	$RH \leq 50\%$ , $T_A = 25^\circ\text{C}$ , $I_{I-O} \leq 10\ \mu\text{A}$ , $t = 1\ \text{minute}$ , $f = 50\ \text{Hz}^{(9)(11)}$	5,000			$V_{RMS}$
$R_{I-O}$	Resistance (Input to Output)	$V_{I-O} = 500\ \text{VDC}^{(9)}$		$10^{11}$		$\Omega$
$C_{I-O}$	Capacitance (Input to Output)	$f = 1\ \text{MHz}$ , $V_{I-O} = 0\text{ V}^{(9)}$		1		pF
$I_{I-I}$	Input-Input Insulation Leakage Current	$RH \leq 45\%$ , $V_{I-I} = 500\ \text{VDC}^{(10)}$ $t = 5\ \text{s}$ , (HCPL2530M/2531M only)		< 1		nA
$R_{I-I}$	Input-Input Resistance	$V_{I-I} = 500\ \text{VDC}^{(10)}$ (HCPL2530M/2531M only)		$10^{12}$		$\Omega$
$C_{I-I}$	Input-Input Capacitance	$f = 1\ \text{MHz}^{(10)}$ (HCPL2530M/2531M only)		0.2		pF

#### Notes:

9. Device is considered a two terminal device: pins 1, 2, 3 and 4 are shorted together and pins 5, 6, 7 and 8 are shorted together.
10. Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together.
11. 5,000  $V_{RMS}$  for 1 minute duration is equivalent to 6,000  $V_{RMS}$  for 1 second duration.

## Typical Performance Curves

For single-channel devices; 6N135M, 6N136M, and HCPL4503M.

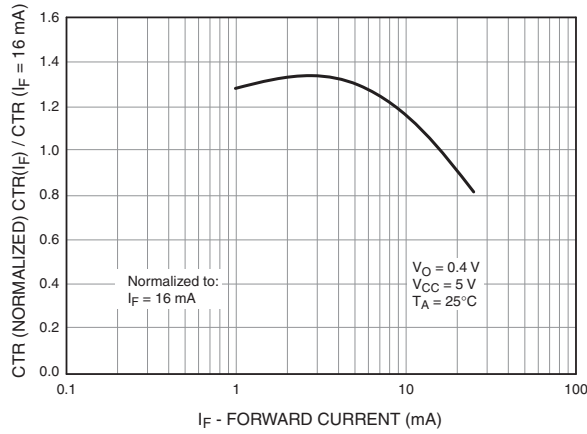


Figure 3. Normalized CTR vs. Forward Current

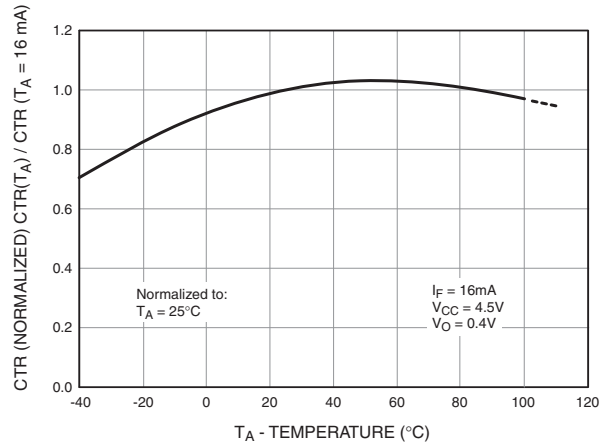


Figure 4. Normalized CTR vs. Temperature

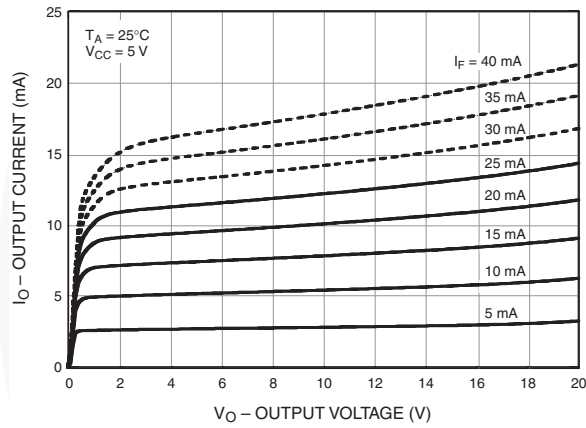


Figure 5. Output Current vs. Output Voltage

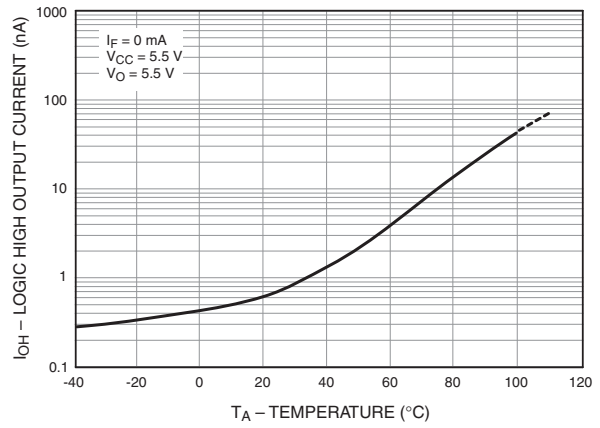


Figure 6. Logic High Output Current vs. Temperature

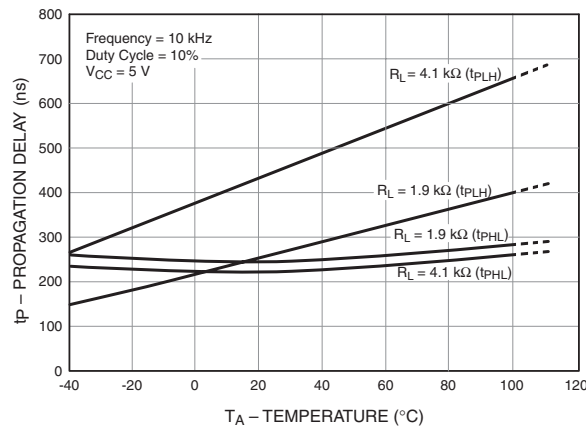


Figure 7. Propagation Delay vs. Temperature

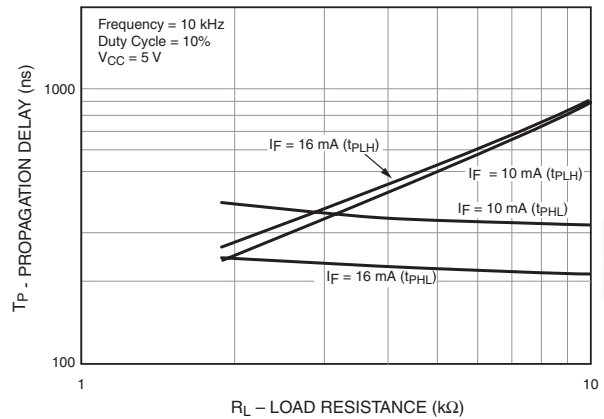


Figure 8. Propagation Delay vs. Load Resistance



### Typical Performance Curves (Continued)

For dual-channel devices; HCPL2530M and HCPL2531M.

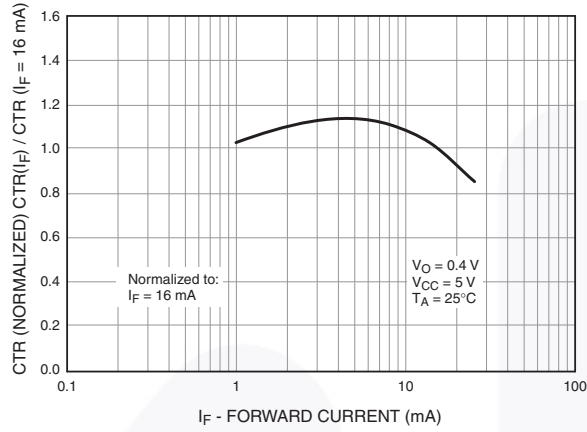


Figure 9. Normalized CTR vs. Forward Current

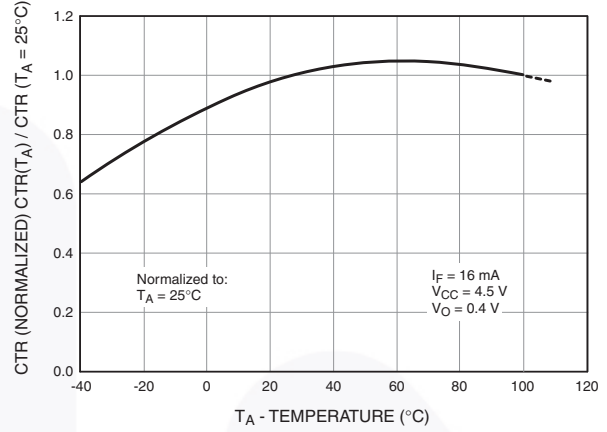


Figure 10. Normalized CTR vs. Temperature

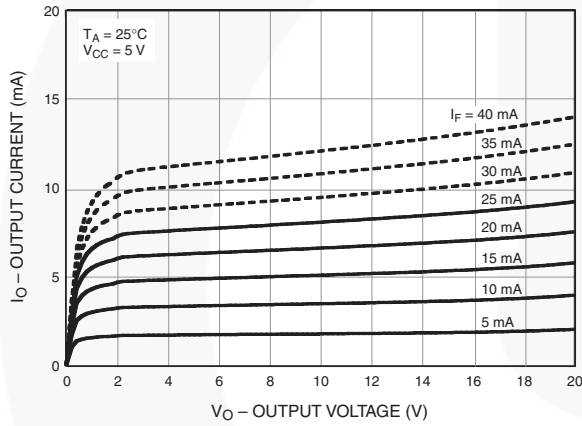


Figure 11. Output Current vs. Output Voltage

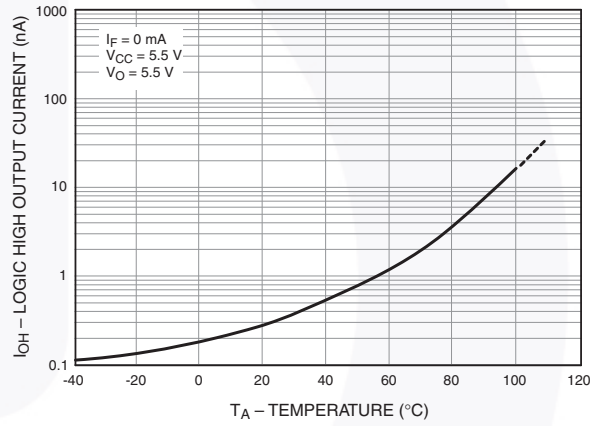


Figure 12. Logic High Output Current vs. Temperature

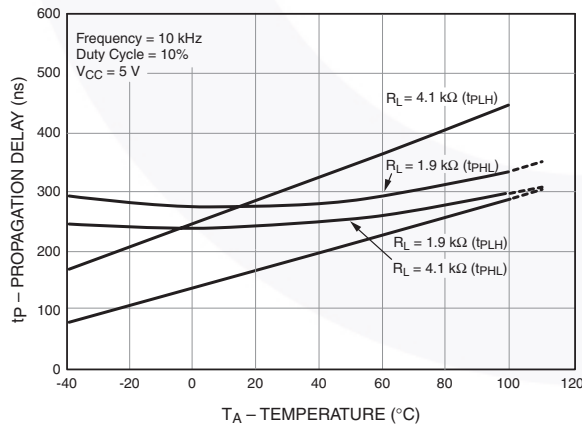


Figure 13. Propagation Delay vs. Temperature

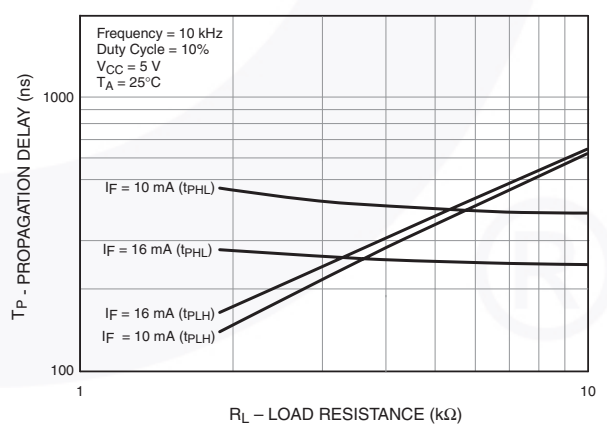


Figure 14. Propagation Delay vs. Load Resistance

### Test Circuits

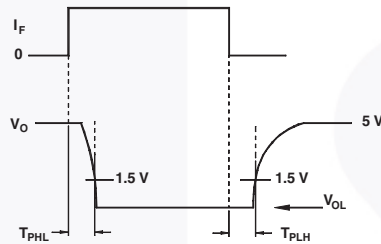
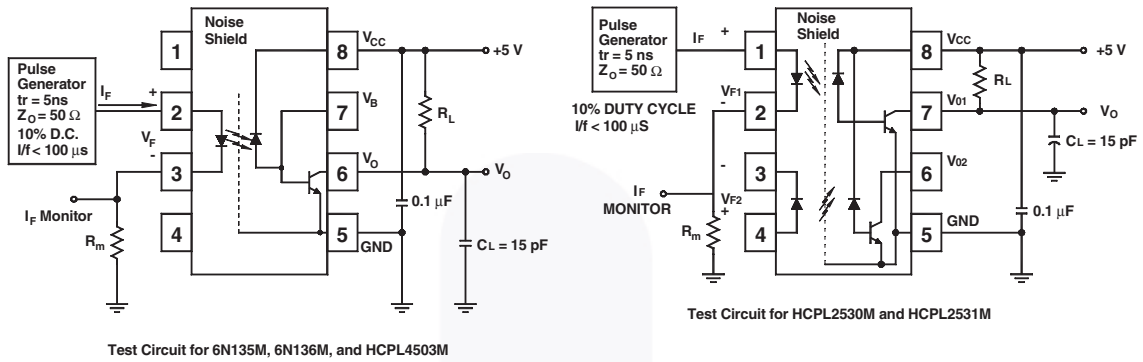


Figure 15. Switching Time Test Circuit

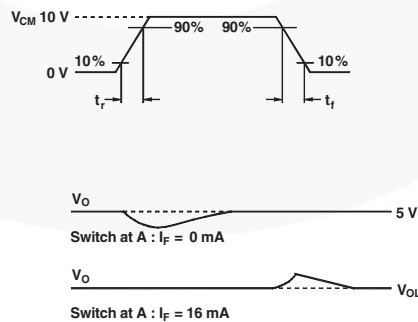
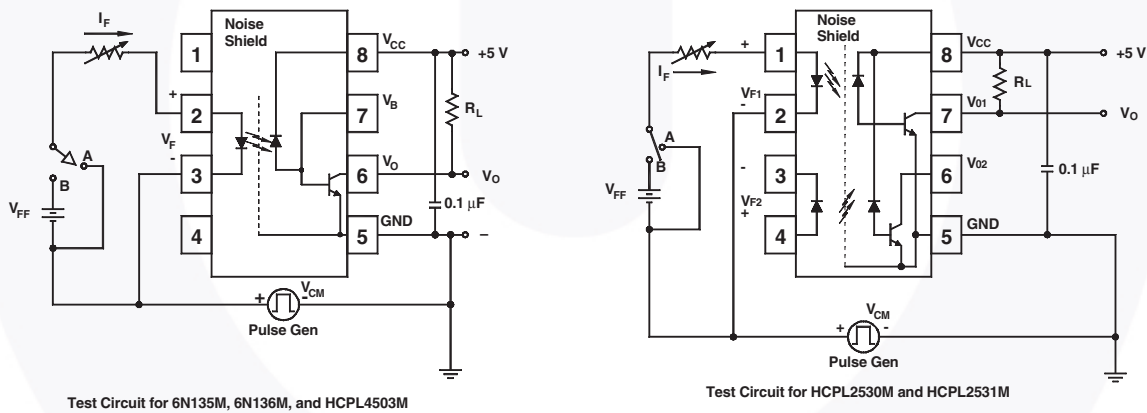
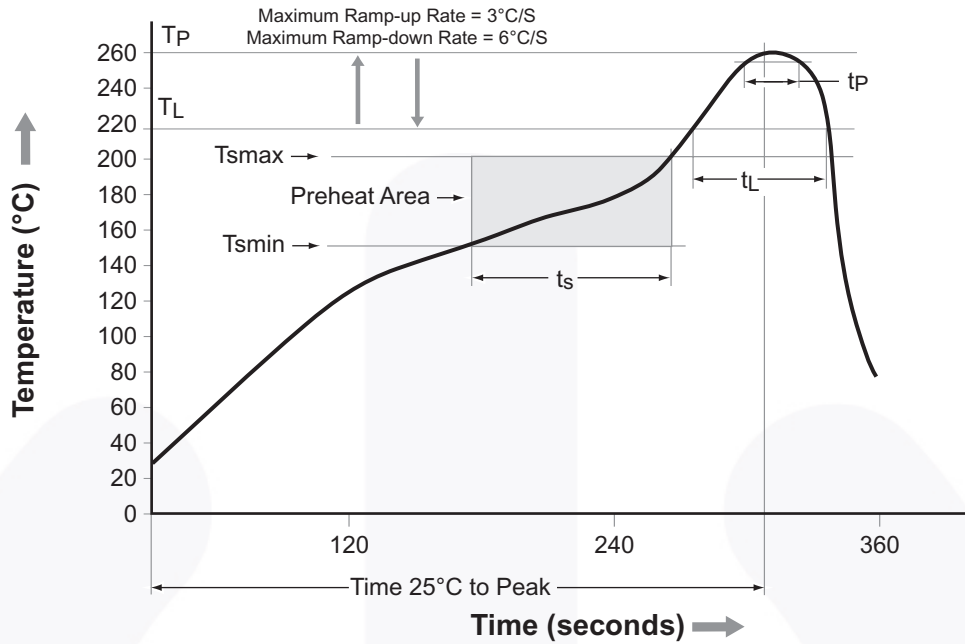


Figure 16. Common Mode Immunity Test Circuit

## Reflow Profile



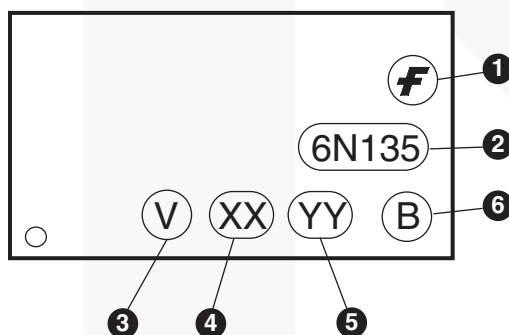
Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60 to 120 s
Ramp-up Rate (t <sub>L</sub> to t <sub>p</sub> )	3°C/second maximum
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 to 150 s
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>p</sub> ) within 5°C of 260°C	30 s
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/s maximum
Time 25°C to Peak Temperature	8 minutes maximum

Figure 17. Relow Profile

## Ordering Information

Part Number	Package	Packing Method
6N135M	DIP 8-Pin	Tube (50 units per tube)
6N135SM	SMT 8-Pin (Lead Bend)	Tube (50 units per tube)
6N135SDM	SMT 8-Pin (Lead Bend)	Tape and Reel (1,000 units per reel)
6N135VM	DIP 8-Pin, DIN EN/IEC 60747-5-5 option	Tube (50 units per tube)
6N135SVM	SMT 8-Pin (Lead Bend), DIN EN/IEC 60747-5-5 option	Tube (50 units per tube)
6N135SDVM	SMT 8-Pin (Lead Bend), DIN EN/IEC 60747-5-5 option	Tape and Reel (1,000 units per reel)
6N135TVM	DIP 8-Pin, 0.4" Lead Spacing, DIN EN/IEC 60747-5-5 option	Tube (50 units per tube)
6N135TSVM	SMT 8-Pin, 0.4" Lead Spacing, DIN EN/IEC 60747-5-5 option	Tube (50 units per tube)
6N135TSR2VM	SMT 8-Pin, 0.4" Lead Spacing, DIN EN/IEC 60747-5-5 option	Tape and Reel (700 units per reel)

## Marking Information

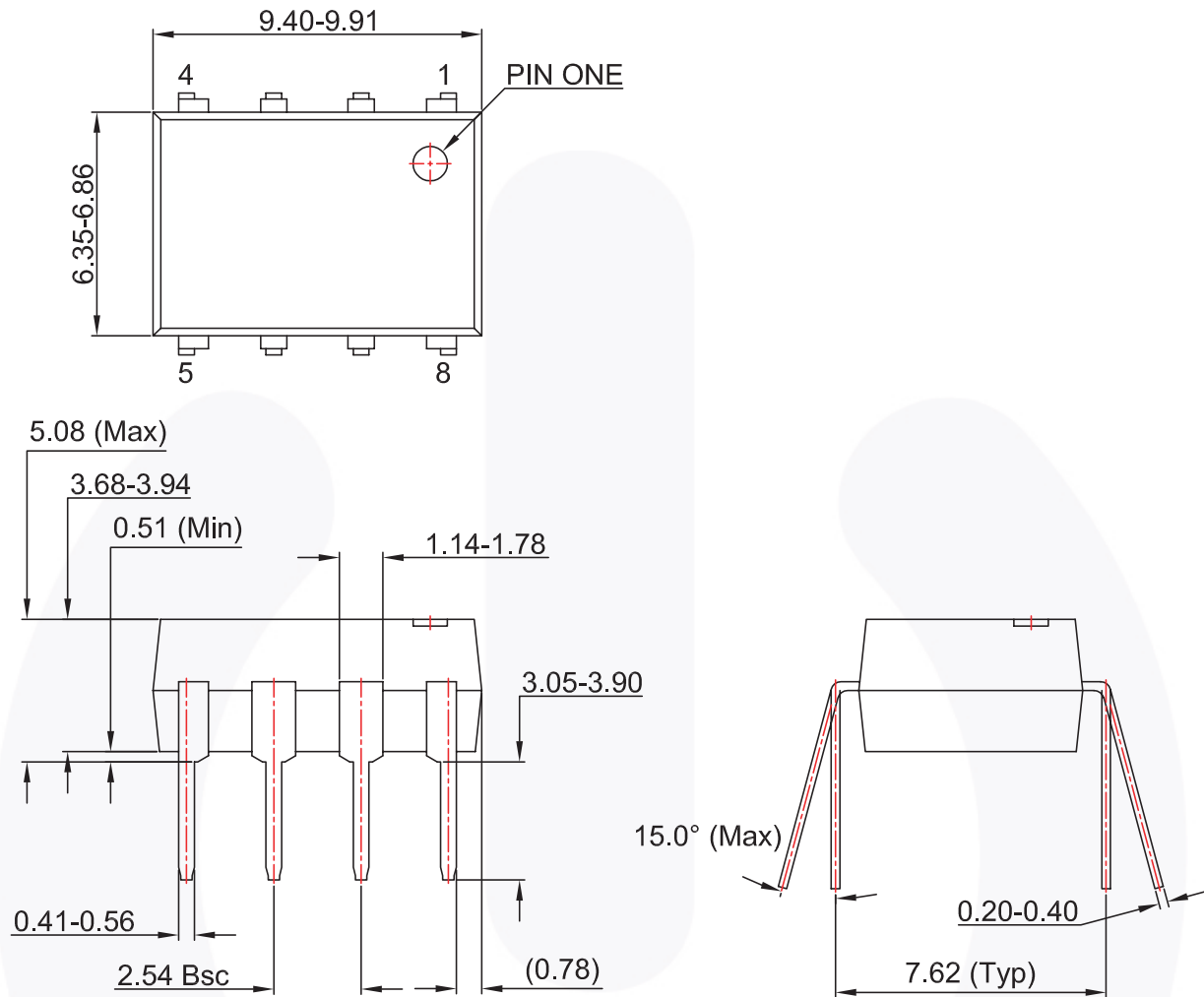


Definitions	
1	Fairchild logo
2 <sup>(1)</sup>	Device number
3	DIN EN/IEC60747-5-5 mark (Note: Only appears on parts ordered with this option – See order entry table)
4	Two-digit year code, e.g., '08'
5	Two-digit work week ranging from '01' to '53'
6	Assembly package code

### Notes:

- 'HCPL' devices are marked with only the numeric characters (for example, HCPL4503M is marked as '4503').
- The 'M' suffix is an ordering identifier only. It is used to indicate the white package version. The 'M' does not appear in the top mark.

## Package Dimensions



### NOTES:

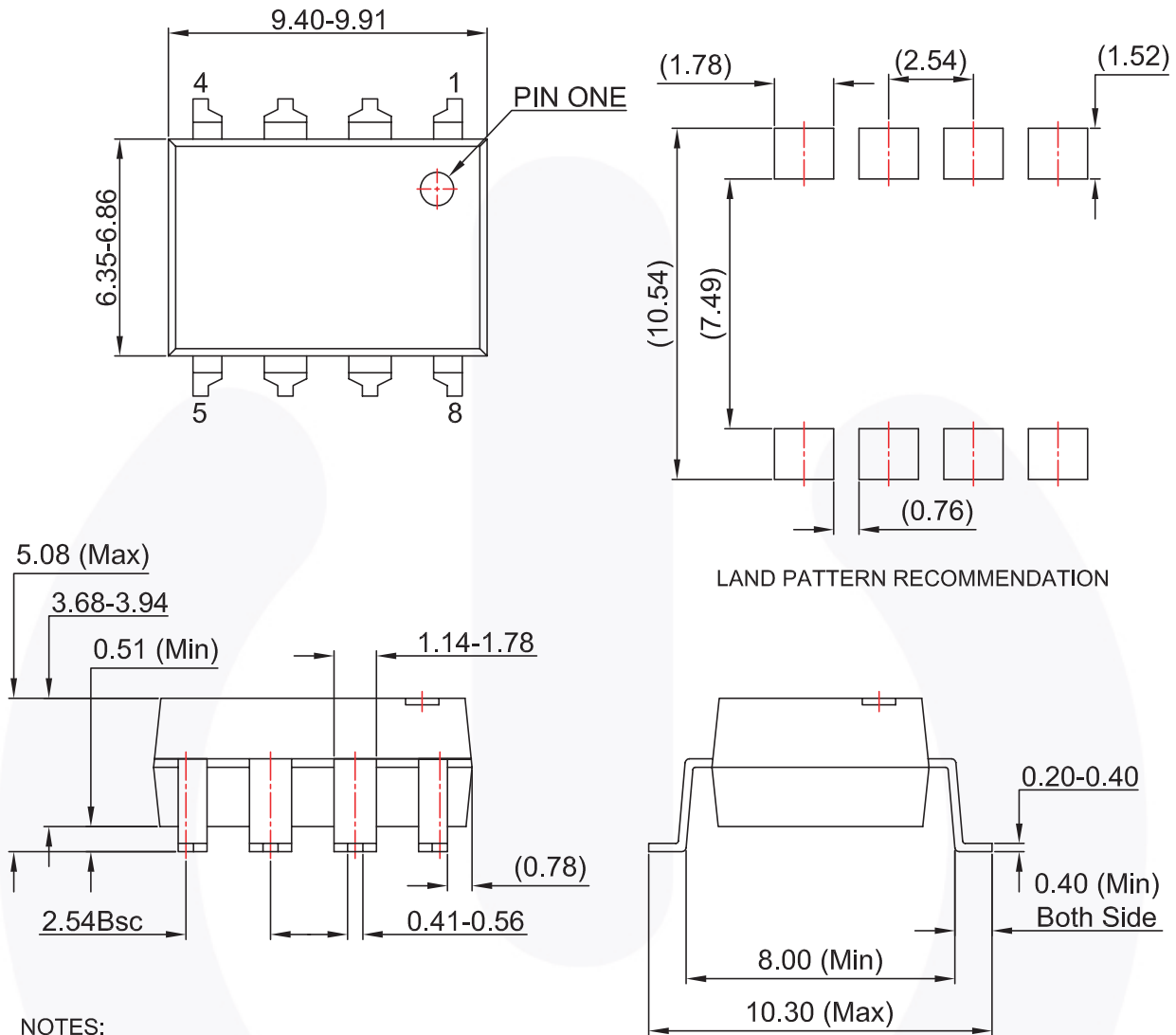
- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N08GREV6.

**Figure 18. 8-Pin DIP Through Hole**

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<http://www.fairchildsemi.com/dwg/N0/N08G.pdf>.

**Package Dimensions** (Continued)



NOTES:

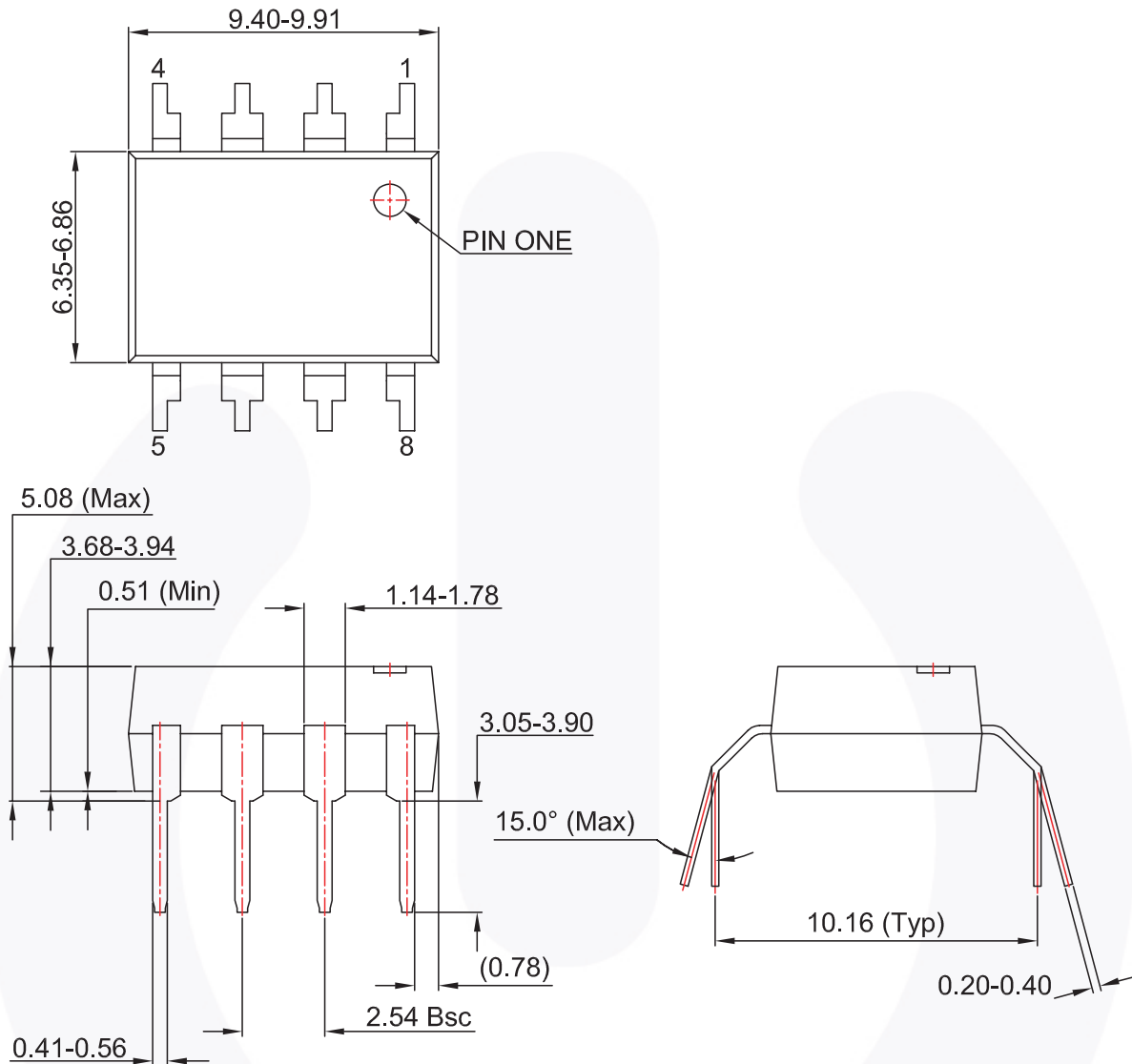
- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N08HREV6.

**Figure 19. 8-Pin DIP Surface Mount (Option S)**

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**Package Dimensions** (Continued)



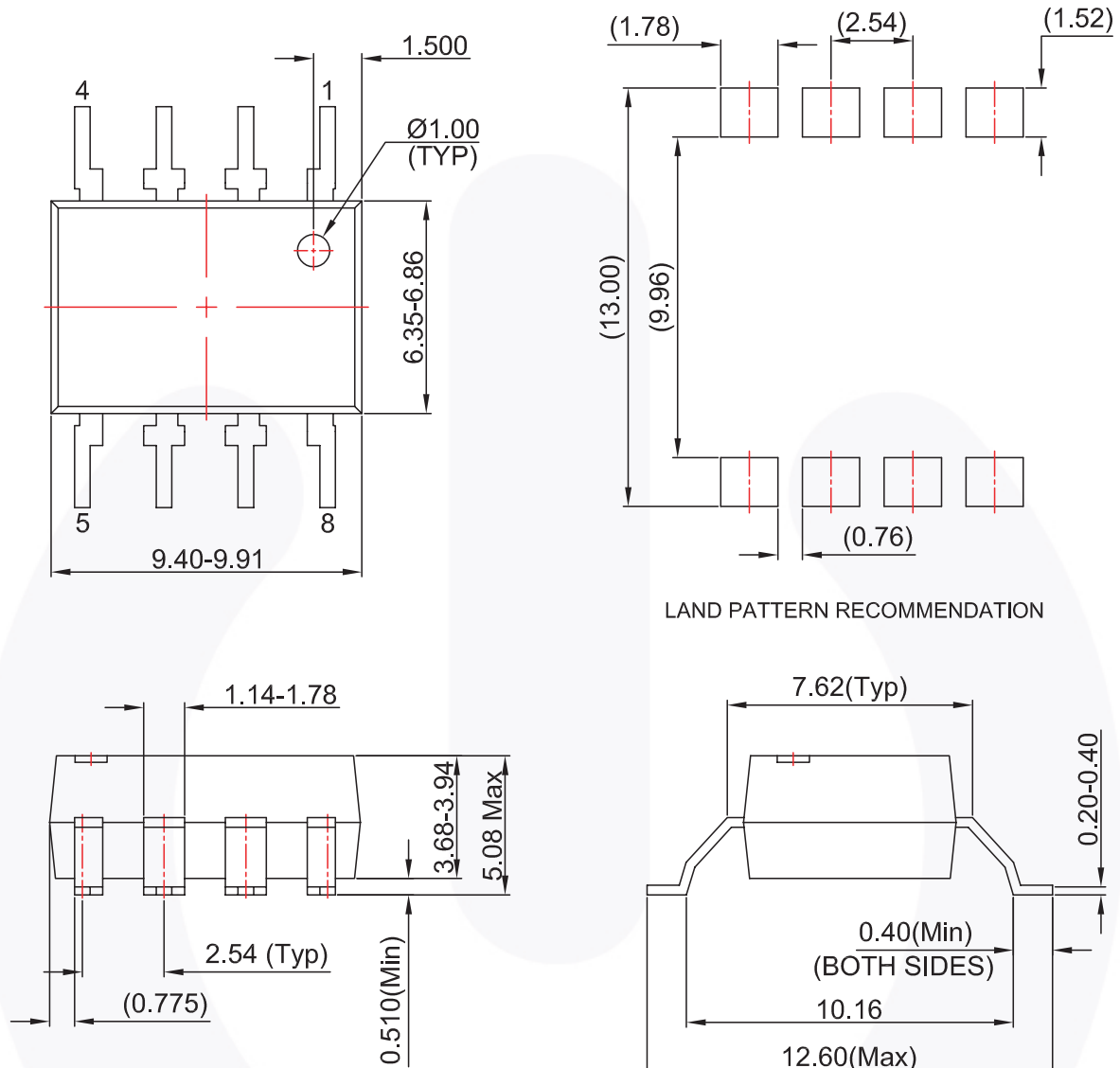
- NOTES:
- A) NO STANDARD APPLIES TO THIS PACKAGE
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
  - D) DRAWING FILENAME AND REVISION: MKT-N08AREV6.

**Figure 20. 8-Pin DIP Through Hole 0.4" Lead Spacing (Option T)**

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**Package Dimensions** (Continued)



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N08L.

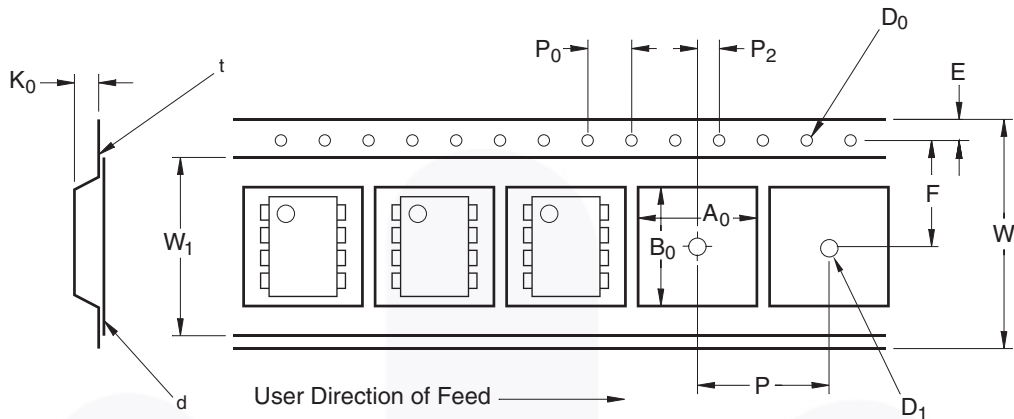
**Figure 21. 8-Pin DIP Surface Mount 0.4" Lead Spacing (Option TS)**

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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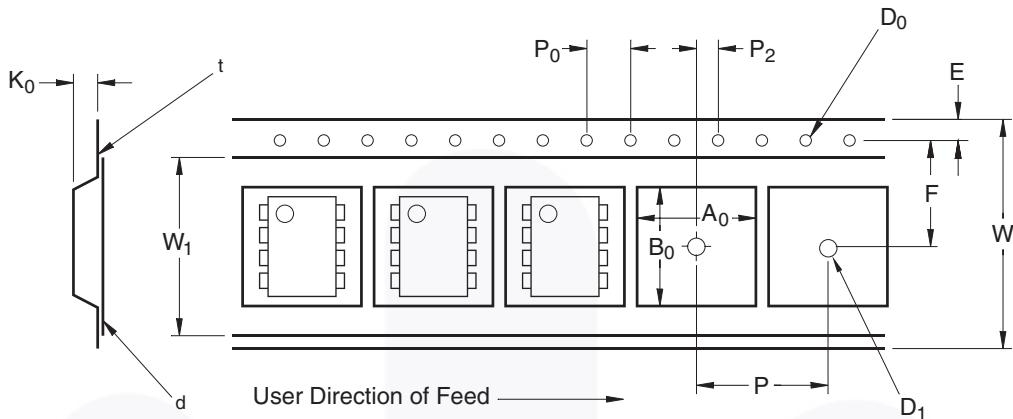


### Carrier Tape Specifications (Option SD)



Symbol	Description	Dimension in mm
W	Tape Width	16.0 ± 0.3
t	Tape Thickness	0.30 ± 0.05
P <sub>0</sub>	Sprocket Hole Pitch	4.0 ± 0.1
D <sub>0</sub>	Sprocket Hole Diameter	1.55 ± 0.05
E	Sprocket Hole Location	1.75 ± 0.10
F	Pocket Location	7.5 ± 0.1
P <sub>2</sub>		2.0 ± 0.1
P	Pocket Pitch	12.0 ± 0.1
A <sub>0</sub>	Pocket Dimensions	10.30 ± 0.20
B <sub>0</sub>		10.30 ± 0.20
K <sub>0</sub>		4.90 ± 0.20
W <sub>1</sub>	Cover Tape Width	13.2 ± 0.2
d	Cover Tape Thickness	0.1 Maximum
	Maximum Component Rotation or Tilt	10°
R	Minimum Bending Radius	30

### Carrier Tape Specifications (Option TSR2)



Symbol	Description	Dimension in mm
W	Tape Width	24.0 ± 0.3
t	Tape Thickness	0.40 ± 0.1
P <sub>0</sub>	Sprocket Hole Pitch	4.0 ± 0.1
D <sub>0</sub>	Sprocket Hole Diameter	1.55 ± 0.05
E	Sprocket Hole Location	1.75 ± 0.10
F	Pocket Location	11.5 ± 0.1
P <sub>2</sub>		2.0 ± 0.1
P	Pocket Pitch	16.0 ± 0.1
A <sub>0</sub>	Pocket Dimensions	12.80 ± 0.1
B <sub>0</sub>		10.35 ± 0.1
K <sub>0</sub>		5.7 ± 0.1
W <sub>1</sub>	Cover Tape Width	21.0 ± 0.1
d	Cover Tape Thickness	0.1 Maximum
	Maximum Component Rotation or Tilt	10°
R	Minimum Bending Radius	30



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